



## Material Content Data Sheet



<b>Sales Product Name</b>		BAS 28 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000740042						
<b>Package</b>		PG-SOT143-4-1		<b>Weight*</b>		11.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.04		365	
	non noble metal	arsenic	7440-38-2	0.000	0.00		4	
	inorganic material	silicon	7440-21-3	0.035	0.31	0.35	3119	3488
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151185	
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208780	359965
wire	noble metal	gold	7440-57-5	0.012	0.11	0.11	1122	1122
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9415	
	inorganic material	antimonytrioxide	1309-64-4	0.156	1.41		14122	
	plastics	brominated resin	-	0.195	1.77		17653	
	plastics	epoxy resin	-	1.628	14.71		147108	
	inorganic material	silicondioxide	60676-86-0	4.427	40.01	58.84	400134	588432
leadfinish	non noble metal	tin	7440-31-5	0.217	1.96	1.96	19578	19578
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27415	27415
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com